

Power MOSFET

120 Amps, 60 Volts

N-Channel D²PAK, TO-220

Features

- Low $R_{DS(on)}$
- High Current Capability
- Avalanche Energy Specified
- AEC Q101 Qualified – NVB5426N
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

MAXIMUM RATINGS (T_J = 25°C Unless otherwise specified)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	60	V
Gate-to-Source Voltage – Continuous			V_{GS}	± 20	V
Gate-to-Source Voltage – Nonrepetitive ($T_P < 10 \mu s$)			V_{GS}	30	V
Continuous Drain Current $R_{\theta JC}$ (Note 1)	Steady State	$T_C = 25^\circ C$	I_D	120	A
		$T_C = 100^\circ C$		85	
Power Dissipation $R_{\theta JC}$ (Note 1)	Steady State	$T_C = 25^\circ C$	P_D	215	W
Pulsed Drain Current	$t_p = 10 \mu s$		I_{DM}	260	A
Operating and Storage Temperature Range			T_J, T_{stg}	-55 to +175	$^\circ C$
Source Current (Body Diode)			I_S	60	A
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^\circ C$ ($V_{DD} = 50 V_{dc}, V_{GS} = 10 V_{dc}, I_{L(pk)} = 70 A, L = 0.3 mH, R_G = 25 \Omega$)			E_{AS}	735	mJ
Lead Temperature for Soldering Purposes, 1/8" from Case for 10 Seconds			T_L	260	$^\circ C$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case (Drain) Steady State (Note 1)	$R_{\theta JC}$	0.7	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

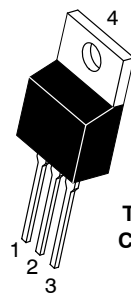
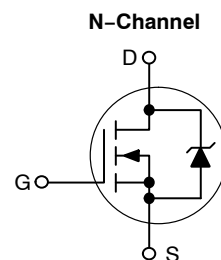
1. Surface mounted on FR4 board using 1 sq in pad size, (Cu Area 1.127 sq in [1 oz] including traces).



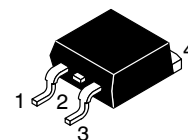
ON Semiconductor®

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V_{(BR)DSS}	R_{DS(ON)} MAX	I_D MAX (Note 1)
60 V	6.0 mΩ @ 10 V	120 A

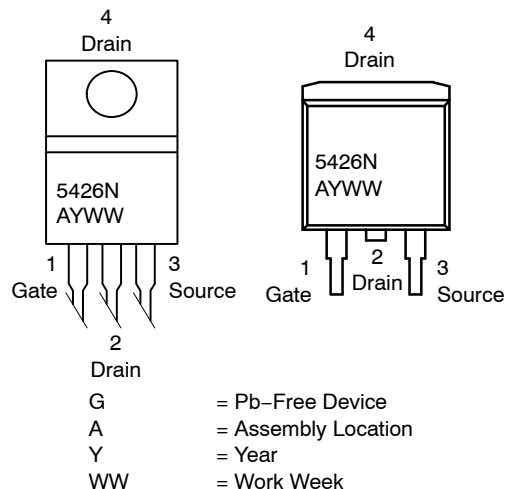


TO-220AB
CASE 221A
STYLE 5



D²PAK
CASE 418B
STYLE 2

MARKING DIAGRAMS & PIN ASSIGNMENTS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

NTB5426N, NTP5426N, NVB5426N

ELECTRICAL CHARACTERISTICS (T_J = 25°C Unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{DS} = 0 V, I _D = 250 μA	60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J			64		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V V _{DS} = 60 V	T _J = 25°C		1.0	μA
			T _J = 150°C		25	
Gate-Body Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA

ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D = 250 μA	2.0	3.1	4.0	V
Negative Threshold Temperature Coefficient	V _{GS(th)} /T _J			9.2		mV/°C
Drain-to-Source On Voltage	V _{DS(on)}	V _{GS} = 10 V, I _D = 60 A		0.3	0.36	V
		V _{GS} = 10 V, I _D = 60 A, 150°C		0.6		
Static Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 60 A		4.9	6.0	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 15 V, I _D = 20 A		65		S

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		5800		pF
Output Capacitance	C _{oss}			1000		
Transfer Capacitance	C _{rss}			370		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 48 V, I _D = 60 A		150	170	nC
Threshold Gate Charge	Q _{G(TH)}			6.0		
Gate-to-Source Charge	Q _{GS}			28		
Gate-to-Drain Charge	Q _{GD}			67		

SWITCHING CHARACTERISTICS, V_{GS} = 10 V (Note 3)

Turn-On Delay Time	t _{d(on)}	V _{GS} = 10 V, V _{DD} = 48 V, I _D = 60 A, R _G = 3.0 Ω		15		ns
Rise Time	t _r			100		
Turn-Off Delay Time	t _{d(off)}			105		
Fall Time	t _f			95		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V _{SD}	V _{GS} = 0 V I _S = 60 A	T _J = 25°C		0.88	1.1	V _{dc}
			T _J = 100°C		0.78		
Reverse Recovery Time	t _{rr}	I _S = 60 A _{dc} , V _{GS} = 0 V _{dc} , di _S /dt = 100 A/μs			75		ns
Charge Time	t _a				50		
Discharge Time	t _b				25		
Reverse Recovery Stored Charge	Q _{RR}				235		μC

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

3. Switching characteristics are independent of operating junction temperatures.

ORDERING INFORMATION

Device	Package	Shipping [†]
NTP5426N	TO-220AB (Pb-Free)	50 Units / Rail
NTB5426NT4G	D ² PAK (Pb-Free)	800 / Tape & Reel
NVB5426NT4G	D ² PAK (Pb-Free)	800 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL CHARACTERISTICS

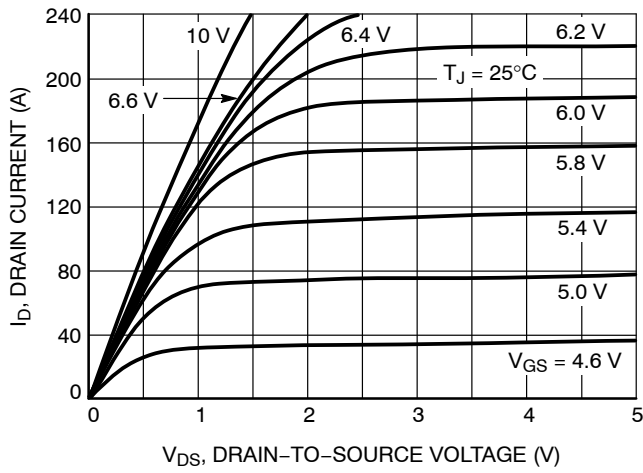


Figure 1. On-Region Characteristics

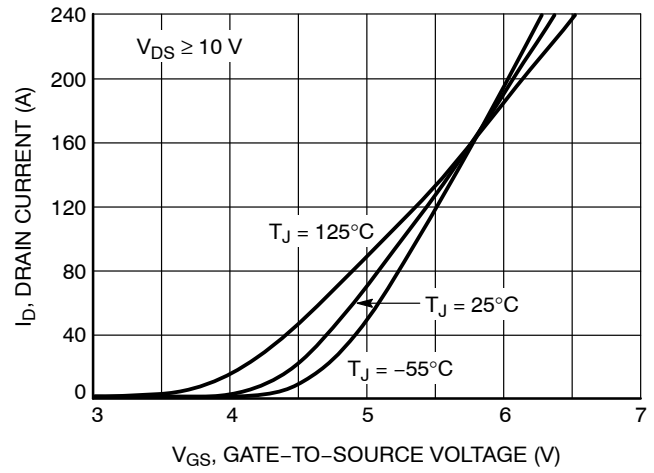


Figure 2. Transfer Characteristics

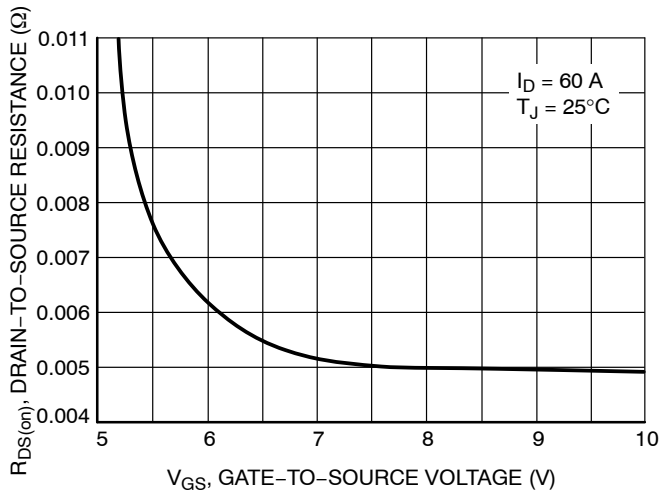


Figure 3. On-Resistance vs. Gate Voltage

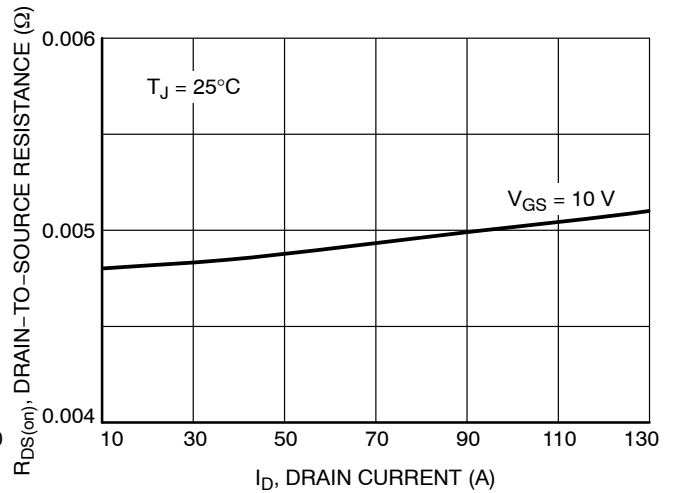


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

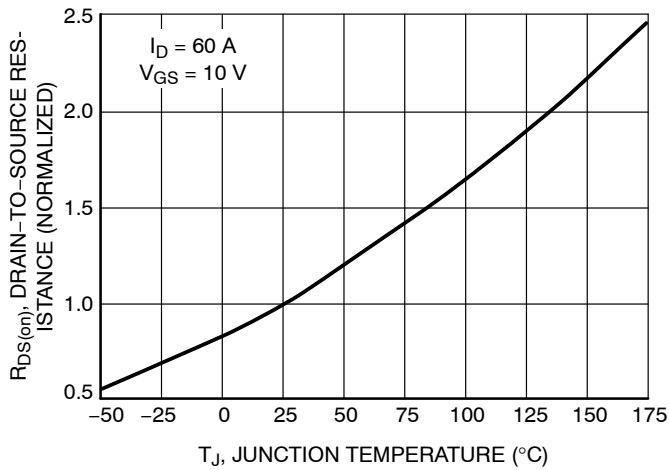


Figure 5. On-Resistance Variation with Temperature

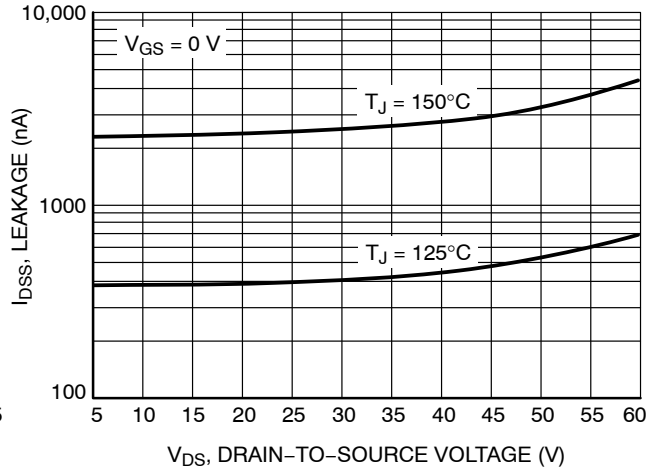


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

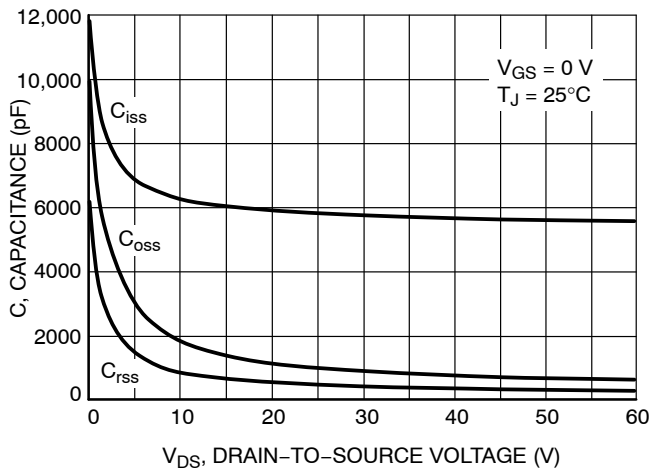


Figure 7. Capacitance Variation

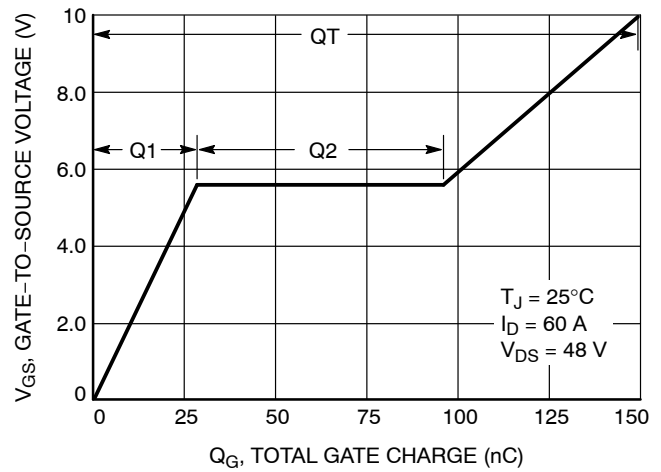


Figure 8. Gate-to-Source Voltage vs. Total Charge

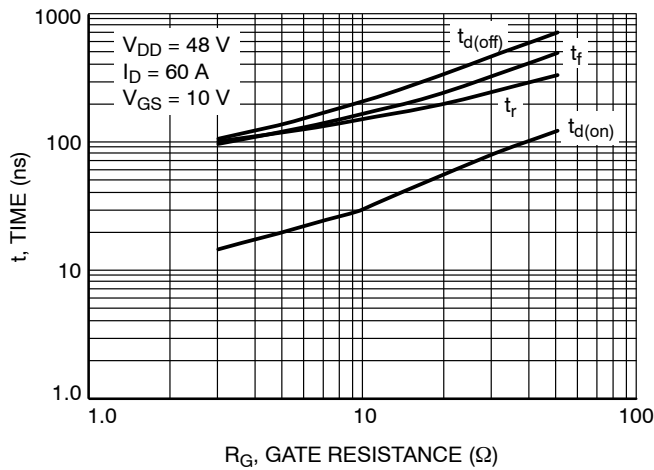


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

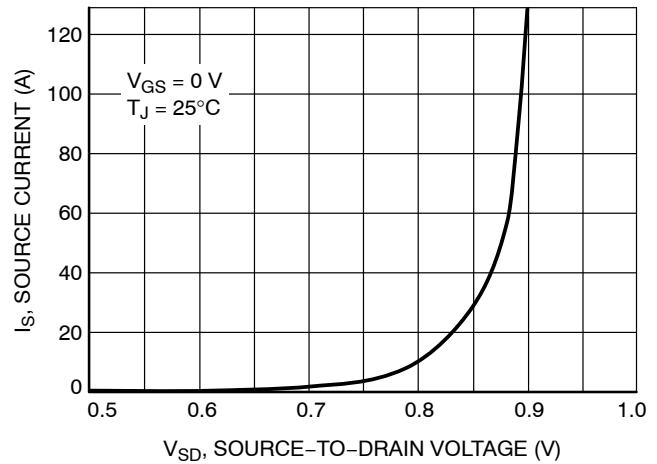


Figure 10. Diode Forward Voltage vs. Current

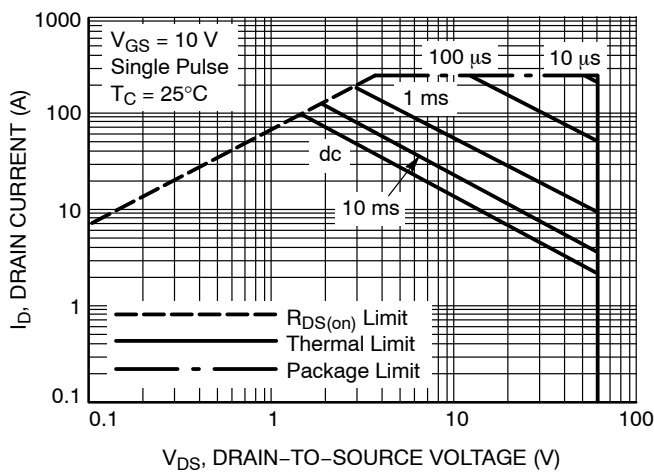


Figure 11. Maximum Rated Forward Biased Safe Operating Area

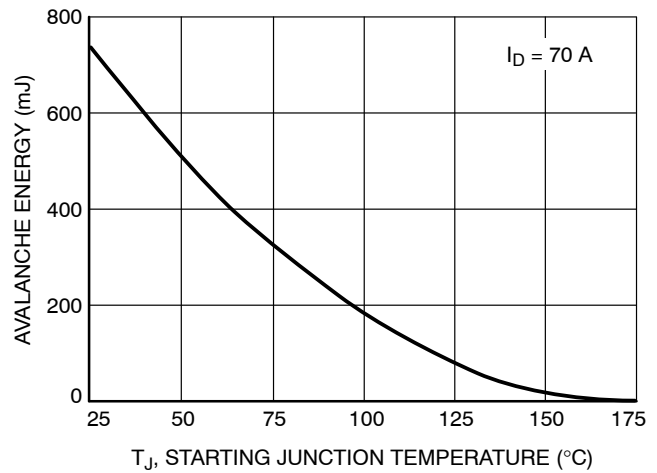


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

TYPICAL CHARACTERISTICS

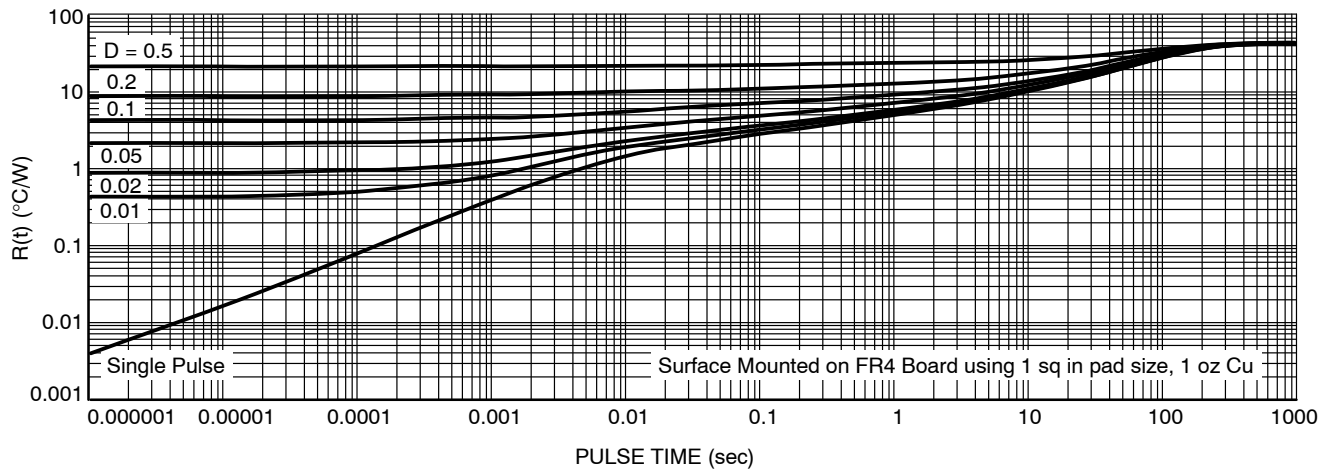


Figure 13. Thermal Response



D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

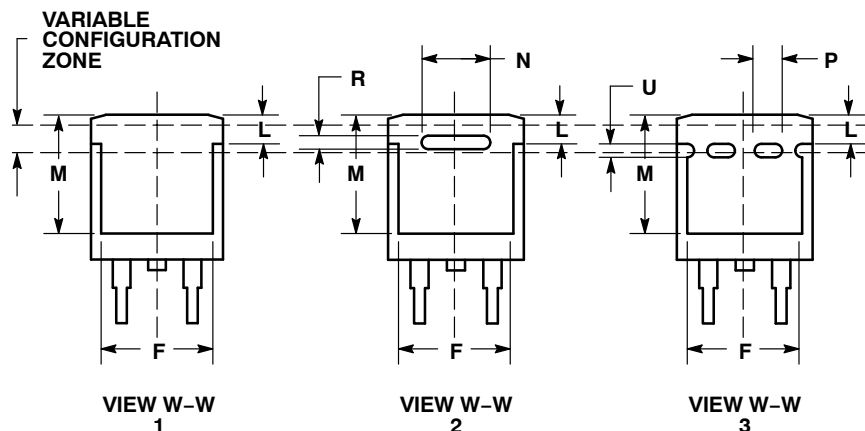
SCALE 1:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE	STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE	STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE
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D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

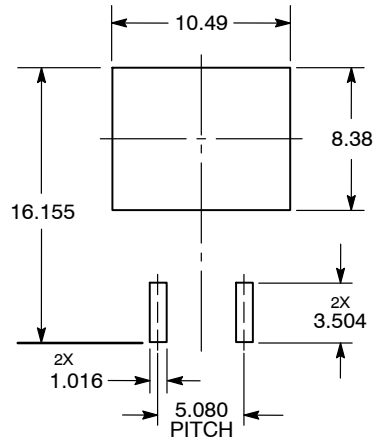
**GENERIC
MARKING DIAGRAM***



xx = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package
AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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